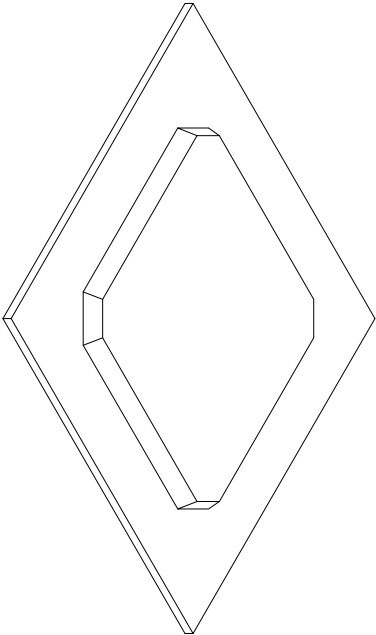


THE DRAWINGS AND INFORMATION CONTAINED HEREIN ARE THE EXCLUSIVE PROPERTY OF AMKOR/ANM. THE INFORMATION, DRAWINGS AND DESIGN CONCEPTS CONTAINED HEREIN ARE CONFIDENTIAL/PROPRIETARY. SHALL BE KEPT IN STRICTLY CONFIDENTIAL AND SHALL NOT BE RELEASED TO ANY THIRD PARTY WITHOUT THE EXPRESS WRITTEN PERMISSION OF AMKOR/ANM.

REVISION HISTORY						
REV	DCN NUMBER	DESCRIPTION	ORIGINATOR	DATABASE FILE NAME	GREYER FILE NAME	INCORPORATOR
00	N/A	INITIAL RELEASE FROM REV "B"	DSRYU	N/A	N/A	DSRYU
01	N/A	ADDED THE NOMINAL LAND SIZE AND PITCH ON THE TOP SIDE	DSRYU	N/A	N/A	DSRYU
02	N/A	CORRECTED PITCH/TOP MATRIX TO 0.065 ADDED AT BALL LAND/TOP, PAGE 4 ADDED 352 SOLDER MATRIX WITH OUT A1 BALL LAND/BOTTOM MARKING, PAGE 5	JMCK	N/A	N/A	JMCK



NOTES: UNLESS OTHERWISE SPECIFIED

1. ALL DIMENSIONS AND TOLERANCES CONFORM TO ASME Y14.5M-1994.

2. PRIMARY DATUM [C] AND SEATING PLANE ARE DEFINED BY THE SPHERICAL CROWNS OF THE SOLDER BALLS.

3. DIMENSION IS MEASURED AT THE MAXIMUM SOLDER BALL DIAMETER, PARALLEL TO PRIMARY DATUM C.

UNLESS OTHERWISE SPECIFIED DIMENSIONS ARE IN MILLIMETERS		THIRD ANGLE PROJECTION		Amkor Technology, Inc. Seoul, Korea Amkor Semiconductor, Inc., Amkor Technology Philippines, Inc.	
DECIMAL XXX ±0.05	ANGULAR ±1°	DESIGNED DSRYU	DATE 06/16/04		
INTERPRET DIM AND TOL PER ASME Y14.5M - 1994		CHECKED BUKHIM	06/16/04		
		PRODUCT MANAGER AKITO Y	06/16/04		
FINISH SEE CROSS SECTION		RELEASED JDKIM	06/29/04	STRIP DWG NUMBER/REV N/A	PKG OUTLINE DWG NO. N/A
DO NOT SCALE DRAWING				SCALE NONE	SHEET 1 OF 5